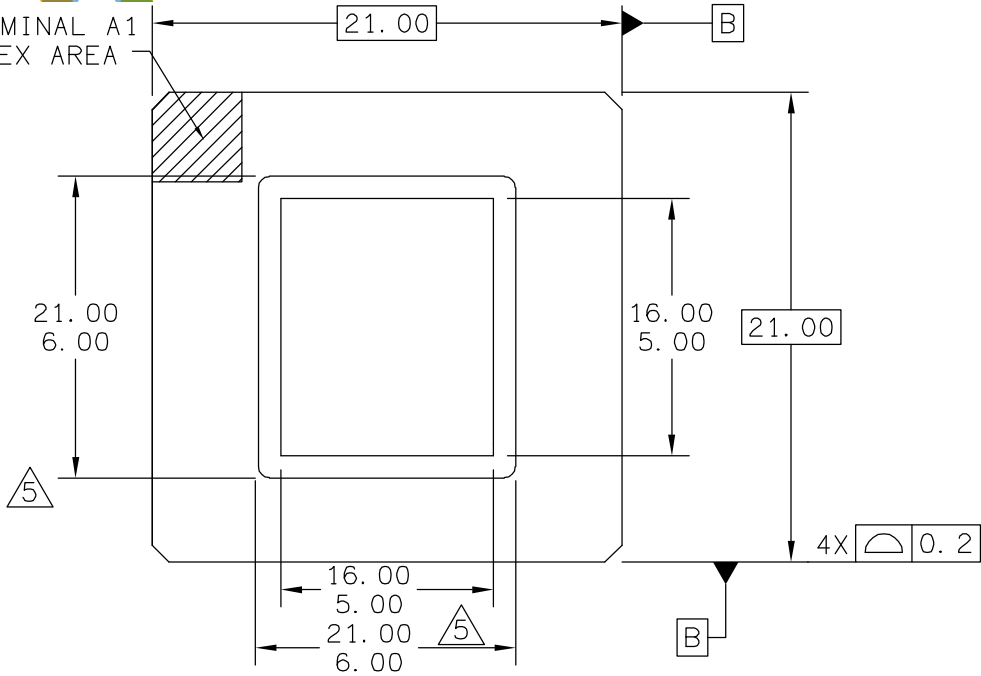
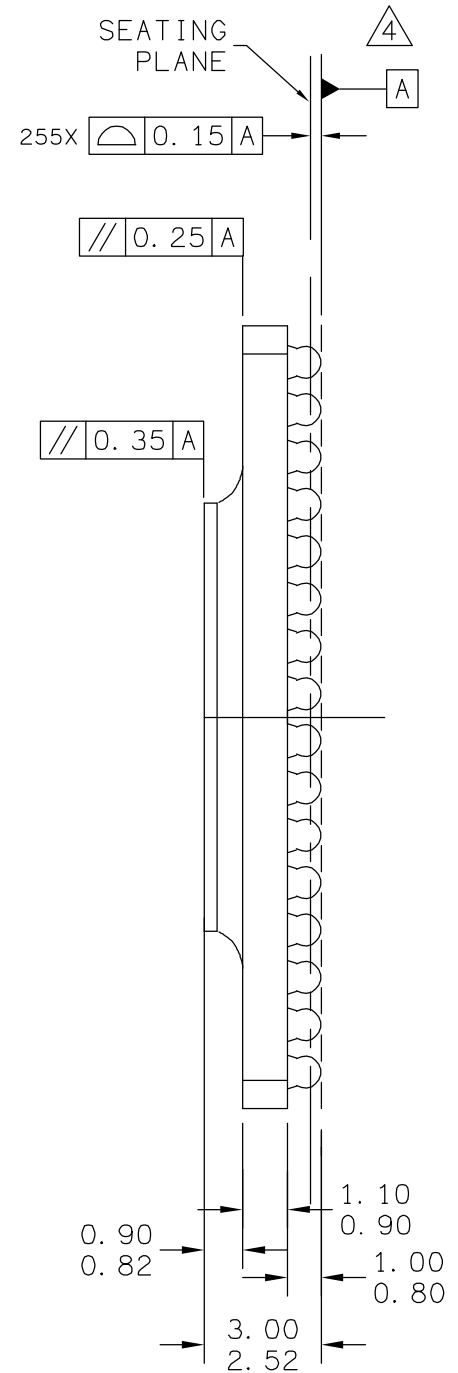




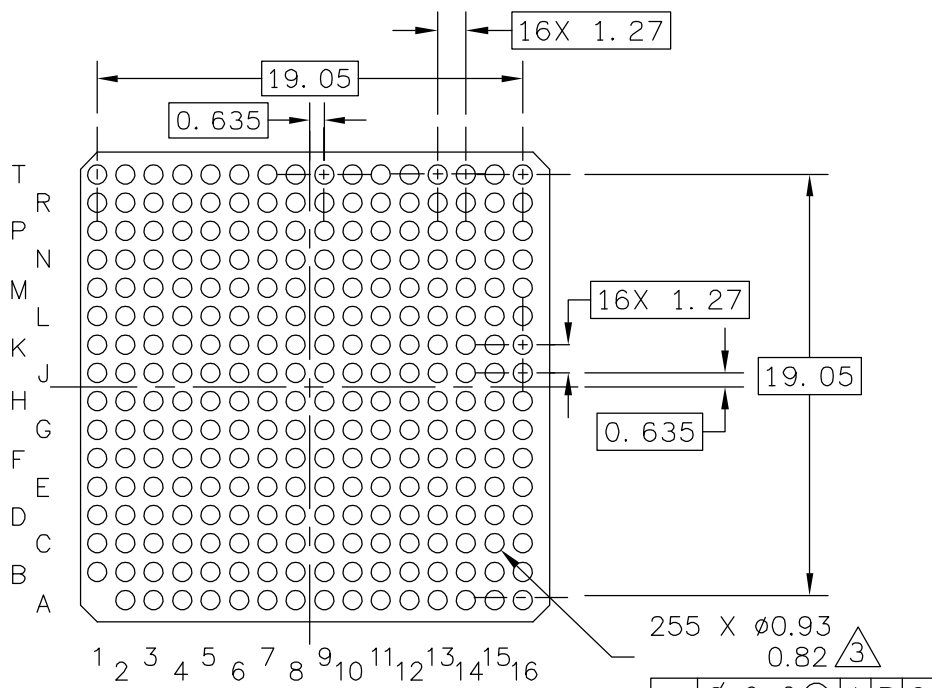
TERMINAL A1  
INDEX AREA



TOP VIEW



SIDE VIEW



BOTTOM VIEW

Φ	Ø 0.3 (M)	A	B	C
Φ	Ø 0.15 (M)	A		

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		STANDARD: JEDEC M0-156 ABG			
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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DIMENSION  $b$  IS THE MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. THE AREA ENCLOSED BY D2 AND E2 MAY CONTAIN CHIPS, CHIP CAPACITORS, AND/OR UNDERFILL, BUT THE HEIGHT OF THESE ITEMS WILL NOT EXCEED THE MAXIMUM OF DIMENSION A.

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